

JPCA Show 50th Anniversary

50th International Electronic Circuits Exhibition

JIEP Microelectronics Show

35th ADVANCED ELECTRONICS PACKAGING EXHIBITION

実装関連展

JISSO KANREN Show



Total Organic Devices Expo

IoT supporting semiconductor /circuit board exhibition



WIRE Japan Show

Electrical /optical transmission technology Exhibition

JEP/TEP Show

JEP Japan Federation Of Electronic Parts Distributors And Dealers
TEP Tokyo Electronics Appliances Wholesalers Association



E-Textile

E-Textile

Smart Sensing

Smart Sensing

INTERNATIONAL OPTOELECTRONICS EXHIBITION

InterOpto

interOpto

LED JAPAN

LED JAPAN

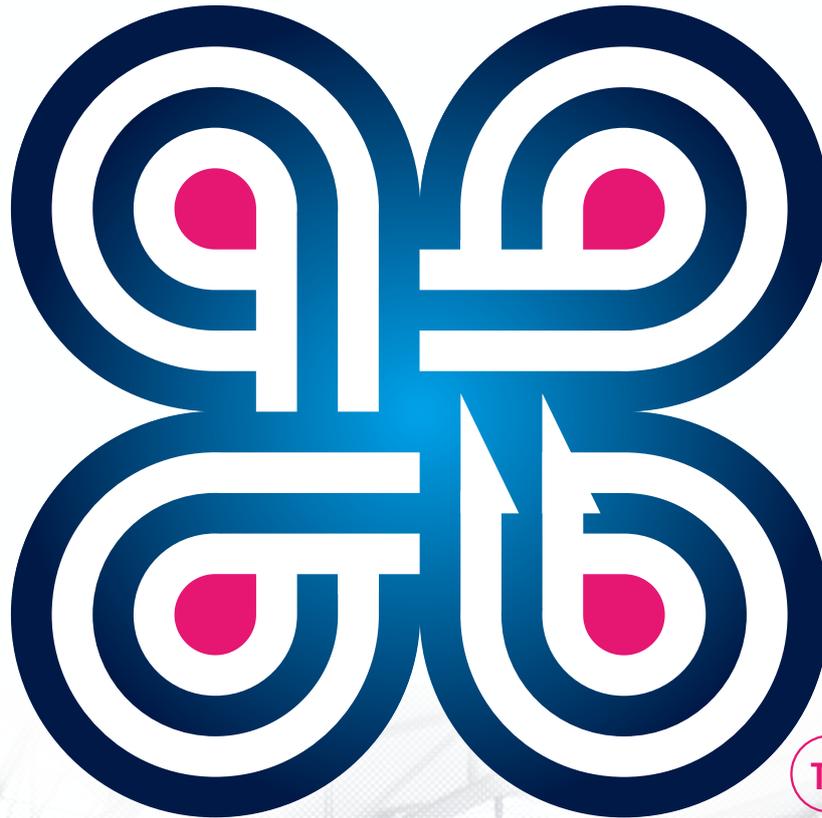
Imaging Japan

Imaging Japan

Edge Computing

Edge Computing

See. Face. Talk.



The Exhibition Guide

2021. 10.27 Wed. → 10.29 Fri.

Tokyo Big Sight South Exhibition Halls

Comprehensive exhibition of technology embodying 5G, automobile, IoT, robots, wearable, advanced optical system, etc.

The Total Solution Exhibition for Electronic Equipment 2021

www.jpcaashow.com



Official Website

Organizers: Japan Electronics Packaging and Circuits Association, Japan Institute of Electronics Packaging, Electronic Device Industry News (Sangyo Times, Inc.), Electric Wire & Cable News (KOGYO TSUSHIN CO., LTD), JTB Communication Design, Inc.
Co-organizers: Japan Federation Of Electronic Parts Distributors And Dealers, Tokyo Electronics Appliances Wholesalers Association, e-Textile research group of Fukui, Optoelectronics Industry and Technology Development Association
Sponsor: Ministry of Economy, Trade and Industry

Overseas Cooperation: World Electronic Circuits Council (WECC) Member Associates: China Printed Circuit Association (CPCA), European Institute of Printed Circuits (EIPC), Hong Kong Printed Circuit Association (HKPCA), IPC-Association Connecting Electronics Industries (IPC), Indian Printed Circuit Association (IPCA), Electronic Industries Association of India (ELCINA), Korea Printed Circuit Association (KPCA), Thailand Printed Circuit Association (THPCA), Taiwan Printed Circuit Association (TPCA)

As of June 1, 2021

Comprehensive exhibition of technology embodying 5G, automobile, IoT, robots, wearable, advanced optical system, etc.

- Highly specialized and focused
- Exhibition of large attendance from all over the world

Exhibition Outline

Our objective is to offer and propose technical information and contribute to the advancement of the electronic circuit industry and all related fields by presenting exhibitions of new contents and solutions related to the electronic circuits and packaging technologies used in all electronic / information and communication / control equipments, as well as sensors and E-Textiles (wearable technology) which have great potential for widespread use.

Exhibition Period	Wednesday, October 27 to Friday, October 29, 2021, 10:00 a.m. - 5:00 p.m.
Venue	Tokyo Big Sight South Exhibition Halls
Managed by	Japan Electronics Packaging and Circuits Association (JPCA)
Secretariat Office	JTB Communication Design, Inc.
Admission	1,000 Yen (including tax) * Free Admission for those who have pre-registered online.

Result of 2019

Venue	Tokyo Big Sight West Hall 1-4+Conference Tower	Number of visitors	44,110 people
Exhibit scale	507 companies / 1,372 spaces	Number of seminar audiences	11,421 people

3 key points of the 2021 Exhibition!

(1) The first 12 exhibitions held concurrently in 2 years!
Newly added 4 exhibitions to expand the Exhibition with a broader theme.



(2) Utilization of seminar
More than 100 seminars held including the keynote lecture !!



(3) New measures to increase the number of visitors

Planned to attract new group of visitors in cooperation with organizations, associations, etc. in Japan and abroad.

Measures will be taken for visitors to visit more exhibition booths through **Stamp Rally (stamp collecting game), a lottery for visitors, etc.**

Exhibitions held inside the exhibition/relevant exhibits

<p>Electronic circuits technology</p>  <p>● PWB Tech Finished Products, Design Technologies, Reliability and Inspection Technologies, Main Materials, Processing Technologies, Materials, and Equipment, Manufacturing Equipment, Environmental Systems, Distribution Systems</p> <p>● Module JAPAN Module board / Module Board mounting / General technology for built-in parts (Finished Products / Related Products / Design / Reliability inspection / Materials/Functional materials / Related equipment / Related system)</p> <p>● Flexible Printed Circuits Products Area General technology for Flexible Printed Circuits (Manufacturing)</p> <p>● EMS Japan General contracted services related to EMS, Electronic electrical equipments, and Semiconductors</p> <p>Organizer: Japan Electronics Packaging and Circuits Association</p>	<p>High-density packaging technologies</p>  <p>35th ADVANCED ELECTRONICS PACKAGING EXHIBITION</p> <p>General technology for implementation and electric technology (Materials / Circuit and Mounting design / High speed high frequency / Electromagnetic properties / Electronic parts / mounting / Optical circuit mounting / Environmental affinity implementation / Semiconductor Package / Micro mechatronics mounting technology / Related Manufacturing equipment)</p> <p>Organizer: Japan Institute of Electronics Packaging</p>	<p>Electronic Component Packaging Technologies</p>  <p>JISSO KANREN Show</p> <p>General technology for Electronic Component Packaging Technologies (Electronic component mounting machine / Semiconductor mounting equipment · System / Inspection technology / Mounting design system / Robots)</p> <p>Organizer: Japan Electronics Packaging and Circuits Association</p>				
<p>New circuit fabrication technology</p>  <p>Total Organic Devices Expo IoT supporting semiconductor circuit board exhibition</p> <p>General technology for Organic Devices (Products and parts of Printed Electronics/ MEMS / Sensor LED / OLED / Applied products for Organic semiconductor)</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, Electronic Device Industry News (Sangyo Times, Inc.)</p>	<p>Electrical/optical transmission technology</p>  <p>WIRE Japan Show Electrical /optical transmission technology Exhibition</p> <p>General transmission technology for using wire and cable (Industrial equipment / Electrical wire, cable and connector / Electric wire processing machine / Wiring material / Wire Harness / Measuring instrument for electric wire and cable / Various devices + D116 / Inspection technology / M2M transmission / Optical transmission)</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, Cable News (KOGYO TSUSHIN CO., LTD)</p>	<p>Semiconductors and Electronic parts</p>  <p>JEP/TEP Show JEP Japan Federation Of Electronic Parts Distributors And Dealers TEP Tokyo Electronics Appliances Wholesalers Association</p> <p>General technology for solutions by Semiconductors and Electronic parts (Semiconductors / Electronic Devices / Sensors / Mechanical Devices / FA control equipments / Measuring instruments / Power Sources / IoT and M2M Solution / Manufacturing solution system)</p> <p>Co-organizers: Japan Federation Of Electronic Parts Distributors And Dealers, Tokyo Electronics Appliances Wholesalers Association</p>	<p>Highly functional textile</p>  <p>E-Textile</p> <p>A mix e-textile of electronic technology, fiber and clothing (General technology for smart textile, stretchable and wearable (Textile material / Conductive material / material / Knitting / weaving technology / Print marking technology / Films)</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, e-Textile research group of Fukui</p>			
<p>Sensor technology</p>  <p>Smart Sensing</p> <p>General technology for Sensor and Sensing System (Sensors, Sensor Nodes, Semiconductors, Parts and Devices, Electronics, Telecommunications Devices, Network Systems, Software, Data Platform, Power Sources, Other Related Devices, Technologies and Services)</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</p>	<p>New! Edge solution technology</p>  <p>Edge Computing</p> <p>Advantageous general edge solutions for areas such as low delay, high safety and low communication volume [Edge Application Areas] Automatic operation system / Factory Automation / Telemedicine / AR/VR / Smart city / Agritech / FinTech / Unmanned store, etc.</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</p>	<p>New! All about Photonics 2021</p> <table border="1"> <tbody> <tr> <td data-bbox="638 927 941 1240"> <p>Optical and next-generation applications / network systems</p>  <p>interOpto</p> <p>Optical devices for Automotive and in-vehicle / Manufacturing and production systems / Data centers / Long-distance communication / Healthcare and medical optical devices / AV and home appliances</p> <p>Organizer: Optoelectronics Industry and Technology Development Association (OITDA) Presented by: JTB Communication Design, Inc.</p> </td> <td data-bbox="941 927 1228 1240"> <p>Deep UV / NIR / LEDs application development</p>  <p>LED JAPAN</p> <p>UV / NIR LEDs / LED package material / Devices / power sources / Measurement / inspection / manufacturing equipment / Optical component / material / LED application finished product (automotive lighting, LED visible light communication, medical lighting)</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</p> </td> <td data-bbox="1228 927 1530 1240"> <p>Image processing / sensing technology</p>  <p>Imaging Japan</p> <p>Various camera / sensor equipments / Image processing equipment / Image recognition / image understanding technology / Instrumentation / measurement technology / LiDAR</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</p> </td> </tr> </tbody> </table>		<p>Optical and next-generation applications / network systems</p>  <p>interOpto</p> <p>Optical devices for Automotive and in-vehicle / Manufacturing and production systems / Data centers / Long-distance communication / Healthcare and medical optical devices / AV and home appliances</p> <p>Organizer: Optoelectronics Industry and Technology Development Association (OITDA) Presented by: JTB Communication Design, Inc.</p>	<p>Deep UV / NIR / LEDs application development</p>  <p>LED JAPAN</p> <p>UV / NIR LEDs / LED package material / Devices / power sources / Measurement / inspection / manufacturing equipment / Optical component / material / LED application finished product (automotive lighting, LED visible light communication, medical lighting)</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</p>	<p>Image processing / sensing technology</p>  <p>Imaging Japan</p> <p>Various camera / sensor equipments / Image processing equipment / Image recognition / image understanding technology / Instrumentation / measurement technology / LiDAR</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</p>
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Companies in each field that are expected to participate

● We invite All about Photonics to expand the customer segment.

- **Related to automobile:**
Aisin Seiki, Asahi Denso, ICHIKOH INDUSTRIES, Calsonic Kansei, Keihin, KOA, KOITO MANUFACTURING, STANLEY ELECTRIC, Sumitomo Wiring Systems, DAIHATSU MOTOR, DENSO, TOKAI RIKI, Toyodenso, TOYOTA MOTOR, NISSAN MOTOR, NHK SPRING, PIONEER, Hitachi Automotive Systems, Hino Motors, SUBARU, Honda Motor, Mazda Motor, MITSUBISHI MOTORS, YAZAKI
- **OA/Robotics:**
OMRON, KEYENCE, Canon, KONICA MINOLTA, CYBERDYNE, SANYO DENKI, JUKI, SEIKO EPSON, Panasonic, Panasonic Smart Factory Solutions, FANUC, FUJI, Fuji Xerox, Mitsubishi Electric, YASKAWA Electric, Yamaha Motor, Ricoh Industry, RICOH JAPAN
- **Related to information and communication:**
Apple, Intel, NHK Media Technology, NTT, NTT DOCOMO, Oki Electric Industry, Korean Broadcasting System (KBS), KYOCERA, KDDI, SoftBank, TOKYO BROADCASTING SYSTEM HOLDINGS (TBS), Toshiba Information Systems (Japan), IBM Japan, NEC, Microsoft Japan, Nihon Unisys, Panasonic, PFU, Hitachi, Huawei, Fujikura, FUJITSU, Murata Manufacturing
- **Related to AV and home electrical appliances:**
LG Electronics, CASIO COMPUTER, Canon, Samsung Electronics, Sharp, Sony, Sony Global Manufacturing & Operations, Sony Semiconductor Solutions, DAIKIN INDUSTRIES, NIKON, PIONEER, Panasonic, FUJITSU GENERAL, YAMAHA, Roland
- Related to medical equipment:**
Olympus, Siemens, SHIMADZU, SHIRAKAWA OLYMPUS, Terumo, Canon Medical Systems, Hitachi High-Technologies, Hitachi Healthcare Manufacturing, Fujifilm, MARK ELECTRONICS, MORITA TOKYO MFG
- **Related to semiconductor device**
Intel, STMicroelectronics, Canon, Samsung Electronics, SCREEN Holdings, Sony, TDK, Tokyo Electron, Toshiba Memory, NIKON, Hitachi High-Technologies, FUJITSU SEMICONDUCTOR, Micron Japan, Renesas Electronics, ROHM
- **Related to aerospace:**
IHI, NEC Space Technologies, JAXA (Japan Aerospace Exploration Agency), SINFONIA TECHNOLOGY, Nabtesco, Nippon Avionics, NEC, Mitsubishi Heavy Industries, Mitsubishi Electric
- **Optical technology:**
Dai Nippon Printing Co., Ltd., Toppan Printing CO., LTD., HOYA CORPORATION, Hamamatsu Photonics K.K., Sumitomo Electric Industries, Ltd., Yokogawa Electric Corporation, LIXIL Corporation, Azbil Corporation, NGK ELECTRONICS DEVICES, INC., NTT Electronics Corporation, KAGA ELECTRONICS CO.,LTD., JVCKENWOOD Corporation, HP Japan Inc., IHI Inspection & Instrumentation Co., Ltd., DISCO Corporation, ALPS ALPINE CO., LTD., CANON MEDICAL SYSTEMS CORPORATION, Sony Imaging Products & Solutions Inc., SEKISUI CHEMICAL CO., LTD., SIGMAKOKI CO.,LTD., Sharp Fukuyama Laser Co., Ltd., NGK INSULATORS, LTD., Nippon Sheet Glass Co., Ltd.
- **Other:**
Japan Maritime Self-Defense Force, Japan Ground Self-Defense Force, Tokyo Gas, Tokyo Electric Power, Central Japan Railway, WEST JAPAN RAILWAY, East Japan Railway, Mizuho Bank
- **Electronic circuit board:**
ADVANTEST, Eastern, IBIDEN, ELNA, Kyoei Sangyo, KYOSHA, KYOCERA, Kyoden, Shirai Electronics Industrial, SHINKO, SHINKO ELECTRIC INDUSTRIES, Sumitomo Electric Printed Circuits, DAISHO DENSHI, Nitto Denko, CMK, NIPPON MEKTRON, Panasonic, Hitachi Chemical, Fujikura, FUJITSU INTERCONNECT TECHNOLOGIES, Meiko Electronics, Yamashita Materials, RISHO KOGYO

Exhibition Fee

Category	1 booth/9m ² *Tax included
Non-Members	Yen 451,000
Members	Yen 385,000

*1 Members of the WECC member associations
(CPCA, EIPC, ELCINA, HKPCA, IPC, IPCA, KPCA, THPCA, TPCA.)

* Size of a booth is 9m² (3m × 3m).

* Booth construction, cleaning, electricity, water Supply, etc. is not included in the exhibition fee.

How to apply

Please apply online on our website. (www.jpccashow.com)

If you use the Application Form, please apply by e-mail or FAX.

Please select the exhibition based on your products, technologies or services and carefully read the "Exhibition Regulations" on the back of the Application Form.

For the exhibition which has the exclusive application form, the relevant exhibition regulations shall be applied.

We will send you an invoice after receiving the Application Form, so please transfer the fee to our account by the due date noted on the invoice (In principle, transfer before the exhibition). The invoice can be downloaded from the exhibitor portal.

Deadline

Tuesday, July 20, 2021

If all spaces are reserved before the deadline, the application will no longer be accepted.

Cancellation charges

If an exhibit is cancelled to suit the exhibitor's circumstances, cancellation charges (full or partial fees) shall apply as below.

Date of receipt of written notice of cancellation	Cancellation charges
Until Tuesday, July 20, 2021	30% of booth fees
Wednesday, July 21 – Monday, August 23, 2021	50% of booth fees
Tuesday, August 24 – Thursday, September 23, 2021	70% of booth fees
From Friday, September 24, 2021 onward	100% of booth fees

Schedule prior to the Exhibition (Tentative)

July	August	September	October
▲ July 20, 2021 Application deadline	▲ Exhibitors' Briefing Mid-August (tentative)	▲ Sending invitations Early September	October 25 to 26 Installation period
		Starting pre-registration to the exhibition Mid-September	October 27 to 29 Exhibition open
		Deadline for submission of application documents Late-September	* Immediate removal on the last day

To give exhibitors as much time as possible to apply, the deadline has been set at a later date than in past years. Booth locations will be announced at the Exhibitors' Briefing.

● Safety measures and policies to be taken by organizers

We will take measures to reduce spread of COVID-19 among participants, organizers and other parties involved in the exhibition, and hold the Exhibition with attention to safety. From now on, in consideration of the policies and requests of the Japanese government, relevant ministries and agencies, and local governments, we will plan and implement the exhibition in cooperation and consultation with the facility side.

● In the event of cancellation of the Exhibition

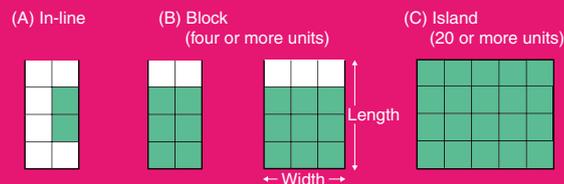
If we decide to cancel the Exhibition due to COVID-19, we will refund the total exhibition fee. * For details, please see the Exhibition Regulations.

**Please refer to the following websites for the most recent information.

> Border enforcement measures to prevent the spread of novel coronavirus (COVID-19) (Ministry of Foreign Affairs of Japan website): https://www.mofa.go.jp/ca/fna/page4e_001053.html

> Situation Report in Japan (Ministry of Health, Labour and Welfare website): https://www.mhlw.go.jp/stf/covid-19/kokunainohasseijoukyou_00006.html#1-1

Booth type



*In some cases, it may not be possible to prepare the requested booth type.

*Requests for a corner booth are not accepted.

Exhibitor Support Program Option

Promotion services will provide an opportunity to increase your presence at the exhibition.

Package booth

● 1 booth / basic plan

Price: 82,500 Yen (Tax included)

This plan includes the minimum necessary booth fixtures and fittings, power supply and carpet.



Managed by

Japan Electronics Packaging and Circuits Association (JPCA)

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Official Website